










Wi-Fi® + Bluetooth®


	Description	Temperature Rating	Host Processor Requirements	Hardware Interfaces	Size	Certified Antenna Options	
  	Sterling-LWB™	2.4 GHz Wi-Fi with Bluetooth 2.1+ EDR, BLE 4.1	-40° to +85°C	Microprocessor to run WLAN TCP/IP stack	SDIO (WLAN), UART (Bluetooth®)	SiP: 10 mm x 10 mm x 1.2 mm Chip antenna or U.FL: 15.5 mm x 21 mm x 2 mm	<ul style="list-style-type: none"> Chip Antenna Dipole via U.FL FlexPIFA via U.FL FlexNotch via U.FL
	TIWi-BLE™	2.4 GHz Wi-Fi with Bluetooth 2.1+ EDR, BLE 4.0 and ANT+	-40° to +85°C	Microprocessor to run WLAN TCP/IP stack	SDIO (WLAN), UART, and Advanced Audio Interface (Bluetooth®)	13 mm x 18 mm x 1.9 mm	<ul style="list-style-type: none"> Off-module chip Dipole via U.FL PIFA via U.FL Flexible Dipole via U.FL
	TIWi5™	2.4 & 5.8 GHz Wi-Fi with Bluetooth 2.1+ EDR, BLE 4.0 and ANT+	-40° to +85°C	Microprocessor to run WLAN TCP/IP stack	SDIO (WLAN), UART, and Advanced Audio Interface (Bluetooth®)	13 mm x 18 mm x 1.9 mm	<ul style="list-style-type: none"> Off-module SMT antenna Dipole via U.FL


Module Certifications:

RCM Certification not available on TIWi-BLE or TIWi5. All certifications pending for Sterling-LWB.


Wi-Fi®

	Description	Temperature Rating	Host Processor Requirements	Hardware Interfaces	Size	Certified Antenna Options	
	TIWi-C-W™	2.4 GHz Stand-alone 802.11 b/g/n Wi-Fi module with ARM Cortex-M3 processor	-40° to +85°C	Development Architecture: Integration directly onto Cortex-M3 processor, or simple integration over UART interface to external MCUs or MPUs	UART	10.5 mm x 10.5 mm x 1.35 mm	<ul style="list-style-type: none"> Off-module chip Dipole via U.FL Waterproof Dipole via U.FL FlexPIFA™ via U.FL



Accelerate your Socket-Based Wi-Fi Implementation

Serial-to-WiFi
API






TiWi-C-W features a cloud agent for the




TiWiConnect™
Module | Cloud | App

cloud-connectivity platform

Module Certifications:







Bluetooth®

	Description	Temperature Rating	Host Processor Requirements	Hardware Interfaces	Size	Certified Antenna Options	
  	SaBLE-x™	2.4 GHz Built in CC2640 single-chip BLE 4.1 with ARM Cortex-M3 processor	-40° to +85°C	Integrated Cortex-M3 can act as MCU or network processor interface for applications running on an external MCU	UART, SPI, I ² C, Digital I/O, and Analog Inputs	11.6 mm x 17.9 mm x 2.3 mm	<ul style="list-style-type: none"> PCB trace antenna Dipole via U.FL FlexPIFA™ via U.FL FlexNotch™ via U.FL
	TIWi-uB1™	2.4 GHz Built in CC2541 single-chip BLE 4.0 with 8051 MCU	-40° to +85°C	Integrated 8051 can act as MCU or network processor interface for applications running on an external MCU	UART, SPI, Digital I/O, and Analog Inputs	11.6 mm x 17.9 mm x 2.3 mm	<ul style="list-style-type: none"> PCB trace antenna Dipole via U.FL
	TIWi-uB2™	2.4 GHz Bluetooth 2.1+ EDR, and BLE 4.0 module	-30° to +85°C	MCU or MPU with a serial port (UART)	HCI, UART, and Audio PCM interfaces	7 mm x 7 mm x 1.5 mm	<ul style="list-style-type: none"> Off-module chip Dipole via U.FL

Featured for SaBLE-x development:



Serial-to-BLE
API

Module Certifications:

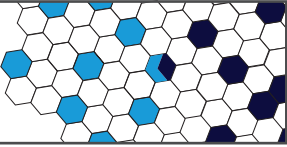
RCM Certification not available on TIWi-uB1 or TIWi-uB2.

802.15.4




	Description	Temperature Rating	Output Power	Receive Sensitivity	Processor	Radio	Size	Certified Antenna Options	
	ProFLEX™	High performance 802.15.4 radios and microcontrollers	-40° to +85°C	100	-98 dBm	MSP430	CC2520	22.8 mm x 41.4 mm	<ul style="list-style-type: none"> Inverted F Dipole via U.FL
	SiFLEX™	High performance 802.15.4 radios and microcontrollers	-40° to +85°C	250	-102 dBm	ATxMega256A3U	AT86RF212B	22.8 mm x 41.4 mm	<ul style="list-style-type: none"> RF castellation Wire Dipole via U.FL Helical

Leverage the Power and Simplicity of FLEXConnect™

- Delivers range extension without the complexities of a full mesh network
- Pre-loaded on both ProFLEX01 and SiFLEX02 modules



Module Certifications for ProFLEX:

Module Certifications for SiFLEX:

